Transfer Molded SiC Power Module

Ultra-compact, low thermal resistance

Features

- The industry's lowest\textsuperscript{1} thermal resistance\textsuperscript{2}
- Ultra-compact, lightweight
- High power density: 15kW/cm\textsuperscript{3}
- Internal parasitic inductance <5nH

\textsuperscript{1}: ROHM August 2018 study
\textsuperscript{2}: Assuming the same chip size, board size and cooling capacity

Applications

- Automotive high-power DC/DC converters
- Main drive inverters in vehicles
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External Appearance

Supports 400A in a compact package

Compact

Water Jacket

(Unit:mm)
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Thermal Resistance (Rthj-W)

Rthj-w : Thermal Resistance Junction to Water

38% less than conventional*

Conventional  Best Rthj-w in the Market  Double-Sided Cooled  Our Latest Version

Assuming the same chip size, board size, and cooling capacity

ROHM R&D Module

DISCOVER THE POWER
Max. Junction Temperature Comparison

Thermal Shock Test (TST): -40°C ↔ +150°C